Features

- Super Low Gate Charge
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

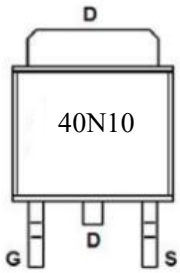
Bvdss	Rdson	ID
100V	25mΩ	40A

Application

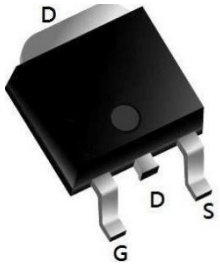
- PWM applications
- Load Switch
- Power management

RoHS

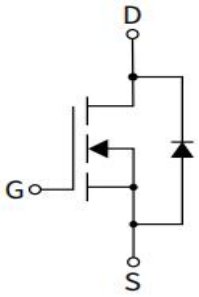
Package



Marking and pin assignment



TO252-3L top view



Schematic diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Quantity
40N10	40N10	TO252-3L	2500

Absolute Maximum Ratings (T_C=25℃unless otherwise specified)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	100	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current,V_{GS}@10V	T_C = 25℃	I_D	40	A
	T_C = 100℃		21	A
Pulsed Drain Current[1]		I_{DM}	120	A
Single Pulsed Avalanche Energy[2]		EAS	30	mJ
Avalanche Current		I_{AS}	-	A
Total Power Dissipation	T_C = 25℃	P_D	42	W
Storage Temperature Range		T_{STG}	-55 ~ 175	℃
Operating Junction Temperature Range		T_J	-55 ~ 175	℃

Thermal Resistance Ratings

Parameter	Symbol	Value	Unit
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	--	℃/W
Thermal Resistance Junction to Case[1]	$R_{\theta JC}$	3.6	℃/W

Ordering Information

Ordering Number	Package	Pin Assignment			Packing
Halogen Free		G	D	S	
HL40N10	TO252-3L	1	2	3	Tape Reel

Electrical Characteristics (T_J=25℃,unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V,I_D=250μA	100	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=100V,V_{GS}=0V	-	-	1	μA
Gate to Body Leakage Current	I_{GSS}	V_{GS}=±20V,V_{DS}=0V	-	-	±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{GS}=V_{DS},I_D=250μA	0.8	1.2	1.6	V
Drain-Source On-Resistance[3]	$R_{DS(on)}$	V_{GS}=10V,I_D=10A	-	25	32.5	mΩ
		V_{GS}=4.5V,I_D=6A	-	26	36	
Total Gate Charge	Q_g	V_{DS}=80V,V_{GS}=4.5V, I_D=20A	-	20	-	nC
Gate-Source Charge	Q_{gs}		-	3.1	-	
Gate-Drain(“Miller”) Charge	Q_{gd}		-	14	-	
Turn-On Delay Time	$t_{d(on)}$	V_{GS}=4.5V,V_{DS}=80V, R_G=3.1Ω,I_D=20A	-	11	-	ns
Rise Time	t_r		-	91	-	
Turn-Off Delay Time	$t_{d(off)}$		-	40	-	
Fall Time	t_f		-	71	-	
Input Capacitance	C_{iss}	V_{DS}=25V, V_{GS}=0V,f=1MHz	-	1964	-	pF
Output Capacitance	C_{oss}		-	90	-	
Reverse Transfer Capacitance	C_{rss}		-	74	-	
Continuous Source Current	I_S	-	-	-	40	A
Maximum Pulsed Drain to Source Diode Forward Current	I_{SM}	-	-	-	120	A
Diode Forward Voltage	V_{SD}	V_{GS}=0V,I_S=20A	-	-	1.2	V

Reverse Recovery Time	t_{rr}	I_F=20A,dI/dt=100A/μs	-	64	-	ns
Reverse Recovery Charge	Q_{rr}		-	152	-	nC

Note :

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. EAS condition : T_J=25℃,V_{DD}=50V,V_G=10V,L=0.5mH,Rg=25Ω,I_{AS}=11A.
3. Pulse Test: Pulse Width≤300 μs, Duty Cycle≤0.5%.

Typical Performance Characteristics

Figure1: Output Characteristics

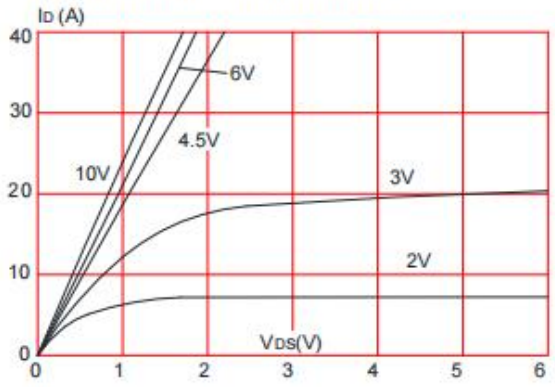


Figure 2: Typical Transfer Characteristics

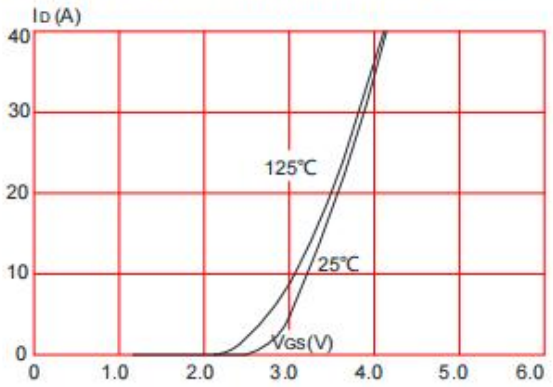


Figure 3: On-resistance vs. Drain Current

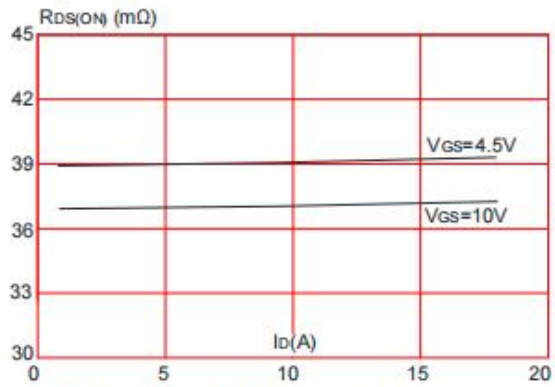


Figure 4: Body Diode Characteristics

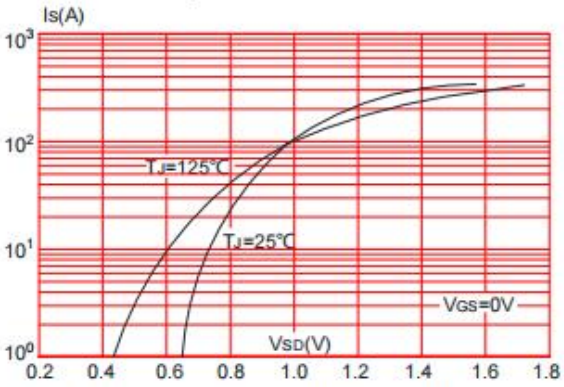


Figure 5: Gate Charge Characteristics

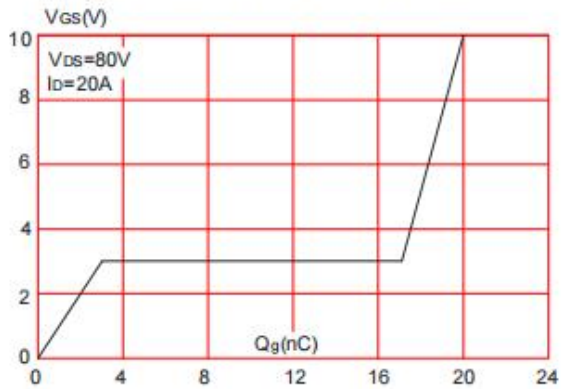


Figure 6: Capacitance Characteristics

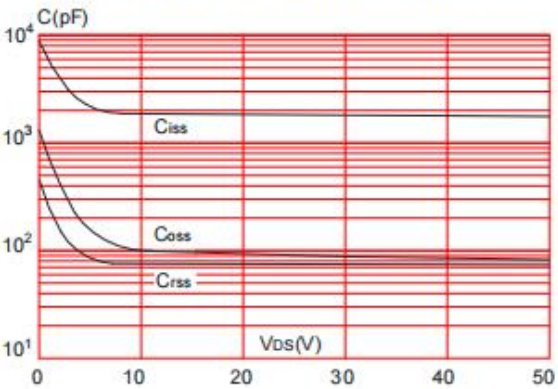


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

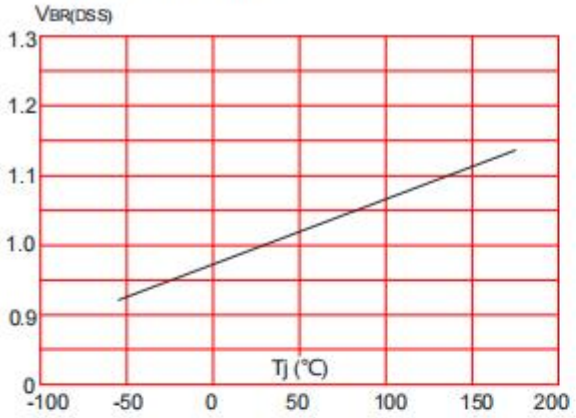


Figure 8: Normalized on Resistance vs. Junction Temperature

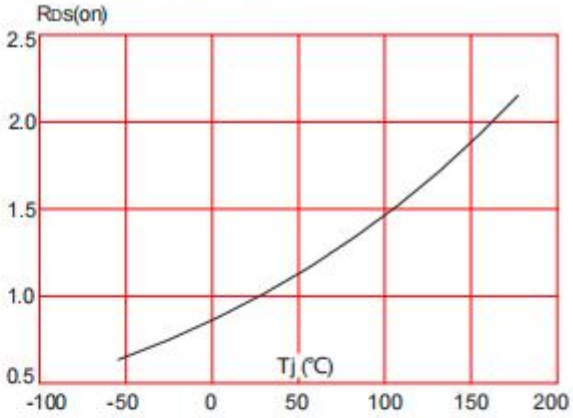


Figure 9: Maximum Safe Operating Area

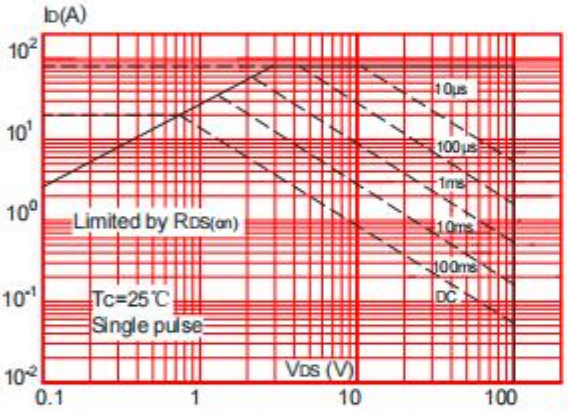


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

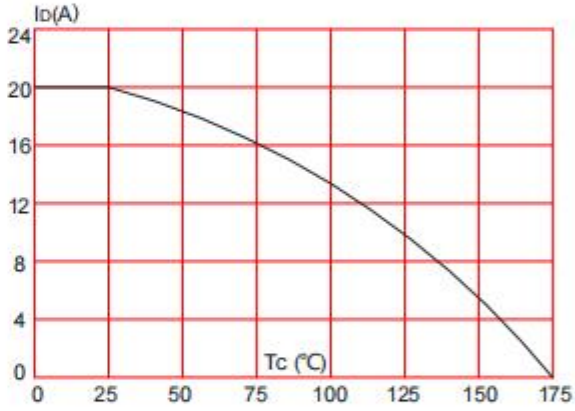
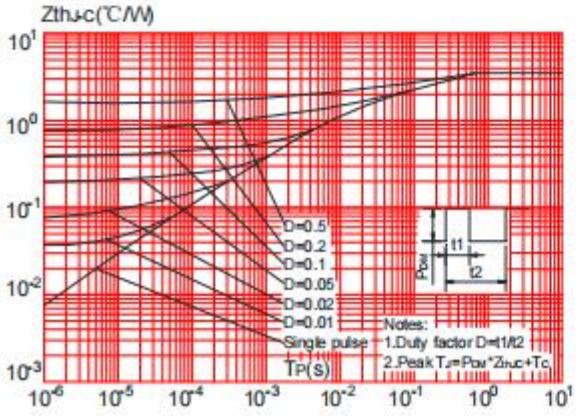
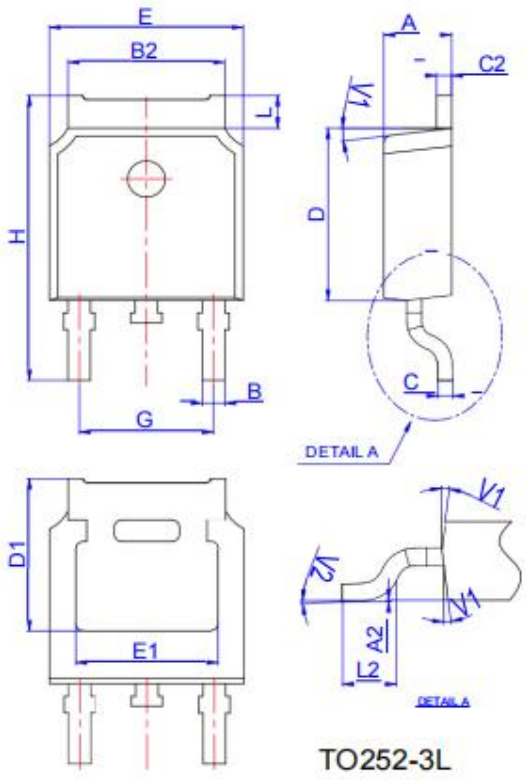


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



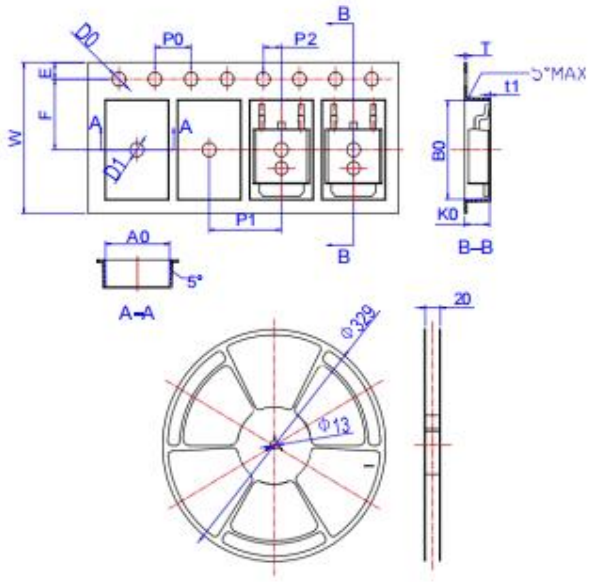
Package Mechanical Data TO252-3L



TO252-3L

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Specification-TO252-3L



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583

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